Title: COMPONENT PACKAGING APPARATUS, SYSTEMS, AND METHODS

IN THE CLAIMS

Please amend the claims as follows.

- 1. (Currently amended) An apparatus comprising:
- an embossing tool substrate made of a first metal, a first major surface of the substrate having an embossing profile with a first major surface and a second major surface;
- a first coating over the first major surface of the substrate, the first coating providing an adherable surface; and
- a second coating over the first coating, the second coating providing a non-adhesive outer surface.
- 2. (Previously presented) The apparatus of claim 1, wherein the first coating further comprises:
 - a layer of a second metal deposited over the embossing tool substrate;
 - a layer of metal oxide deposited over the layer of the second metal; and
 - a layer of metal nitride deposited over the layer of metal oxide.
- 3. (Original) The apparatus of claim 1, wherein the first coating further comprises:
 - a layer of zirconium deposited over the embossing tool substrate;
 - a layer of zirconium oxide deposited over the layer of zirconium; and
 - a layer of zirconium nitride deposited over the layer of zirconium oxide.
- 4. (Original) The apparatus of claim 1, wherein the second coating comprises polypara-xylylene.
- 5. (Original) The apparatus of claim 3, wherein the zirconium layer is about 0.5 microns thick, the zirconium oxide layer is about 0.5 microns thick, the zirconium nitride layer is about 0.5 microns thick, and the second coating comprises poly-para-xylylene and is between about 2 microns and about 9 microns thick.

Filing Date: December 31, 2003

Title: COMPONENT PACKAGING APPARATUS, SYSTEMS, AND METHODS

- 6. (Original) The apparatus of claim 5, wherein the zirconium layer is 0.5 microns thick, the zirconium oxide layer is 0.5 microns thick, the zirconium nitride layer is 0.5 microns thick, and the second coating is between 2 microns and 9 microns thick.
- 7. (Canceled).
- 8. (Original) The apparatus of claim 2, wherein the second coating comprises poly-para-xylylene.
- 9-10. (Canceled).
- 11. (Original) The apparatus of claim 1, further comprising:
 a heater apparatus to provide heat during an embossing operation; and
 a pressure apparatus to apply pressure during the embossing operation.
- 12. (Original) The apparatus of claim 1, wherein the first coating further comprises a layer of zirconium deposited over the embossing tool substrate, and wherein the second coating comprises zirconium nitride deposited over the layer of zirconium.
- 13. 26. (Canceled)
- 27. (New) An apparatus comprising:

an embossing tool substrate made of a first metal, a major surface of the substrate having an embossing profile with a first major surface and a second major surface;

- a first coating over the first major surface of the substrate, the first coating providing an adherable surface, wherein the first coating further comprises:
 - a layer of a second metal deposited over the embossing tool substrate;
 - a layer of metal oxide deposited over the layer of the second metal; and
 - a layer of metal nitride deposited over the layer of metal oxide; and

Filing Date: December 31, 2003

Title: COMPONENT PACKAGING APPARATUS, SYSTEMS, AND METHODS

a second coating over the first coating, the second coating providing a non-adhesive outer surface, and wherein the second coating comprises poly-para-xylylene.

- 28. (New) The apparatus of claim 27, wherein the layer of a second metal is zirconium, wherein the layer of metal oxide is zirconium oxide, and wherein the layer of metal nitride is zirconium nitride.
- 29. (New) The apparatus of claim 27, wherein the layer of a second metal is zirconium, wherein the layer of metal oxide is zirconium oxide, and wherein the layer of metal nitride is zirconium nitride, and wherein the second coating comprises poly-para-xylylene.
- 30. (New) The apparatus of claim 27, further comprising:a heater apparatus to provide heat during an embossing operation; anda pressure apparatus to apply pressure during the embossing operation.